

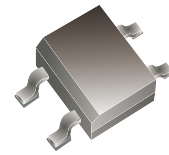
AABS110-HF

Reverse Voltage: 1000 Volts

Forward Current: 1.0 A

RoHS Device

Halogen Free

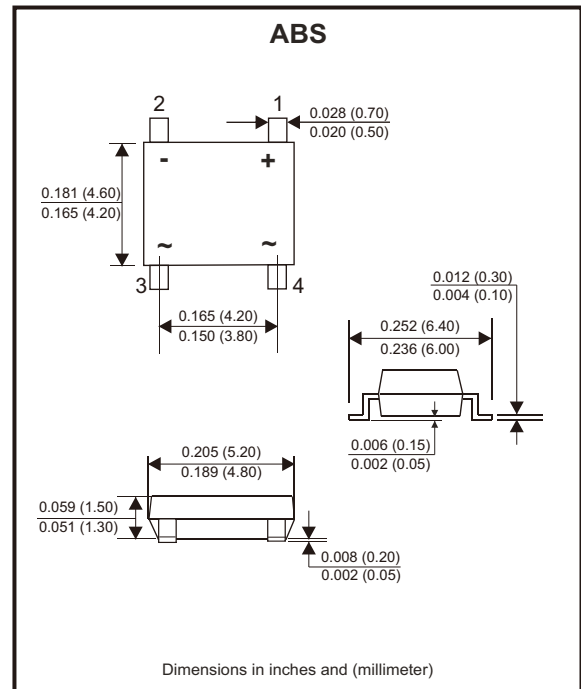


Features

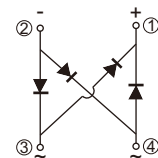
- Glass passivated chip.
- Ideal for automatic placement.
- High surge forward current capability.
- Reliable low cost construction utilizing molded plastic technique.
- Lead tin plated copper.
- AEC-Q101 Qualified

Mechanical data

- Case: ABS, molded plastic.
- Polarity: Symbol molded on body.
- Mounting position: Any.



Circuit Diagram



Maximum Rating and Electrical Characteristics

Rating at $T_A=25^{\circ}\text{C}$, unless otherwise noted.
 Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Parameter	Symbol	AABS110-HF	Unit
Maximum recurrent peak reverse voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC blocking voltage	V_{DC}	1000	V
Maximum average forward rectified current @ $T_A=40^{\circ}\text{C}$ (Note 1)	$I_{(AV)}$	1	A
Peak forward surge current, 8.3ms single half sine-wave, superimposed on rated load (JEDEC Method)	I_{FSM}	30	A
Peak forward voltage per diode at 1.0A DC	V_F	1.05	V
Maximum DC reverse current at rated DC Blocking Voltage per diode @ $T_J=25^{\circ}\text{C}$ @ $T_J=125^{\circ}\text{C}$	I_R	5 100	μA
I^2t rating for fusing ($t < 8.3\text{ms}$)	I^2t	3.7	A^2s
Typical thermal resistance junction to ambient	$R_{\theta JA}$	80	$^{\circ}\text{C/W}$
Operating junction temperature range	T_J	-55 to +150	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^{\circ}\text{C}$

Notes: 1. Mounted on P.C. board.

Company reserves the right to improve product design, functions and reliability without notice.

REV:A

Rating and Characteristic Curves (AABS110-HF)

Fig.1 - Forward Current Derating Curve

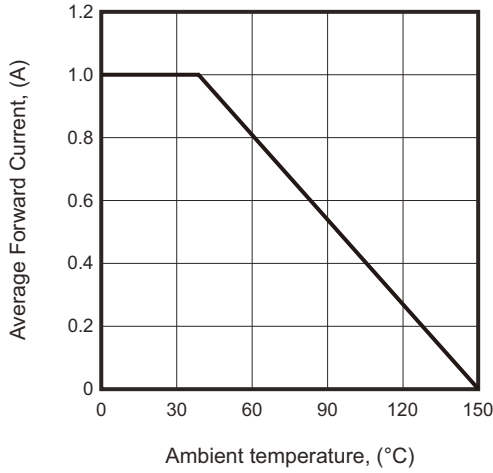


Fig.2 - Maximum Non-Repetitive Surge Current

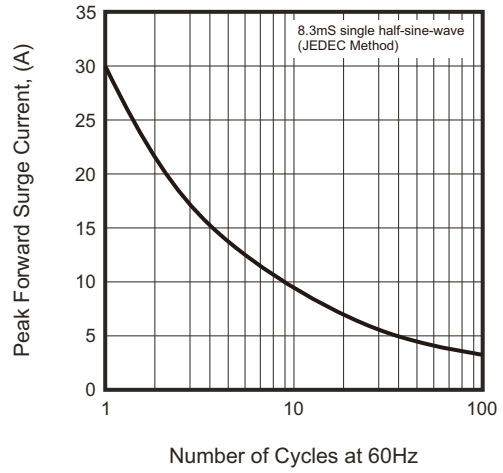


Fig.3 - Typical Reverse Characteristics

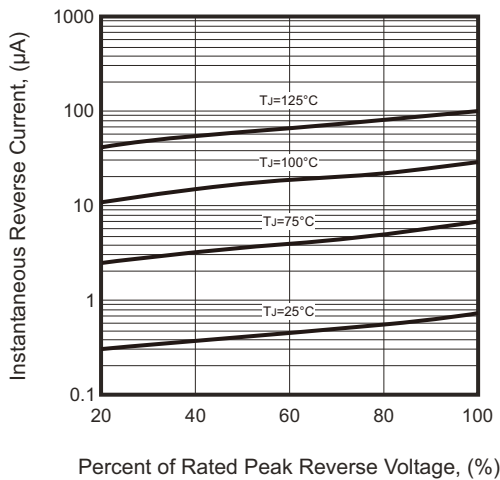
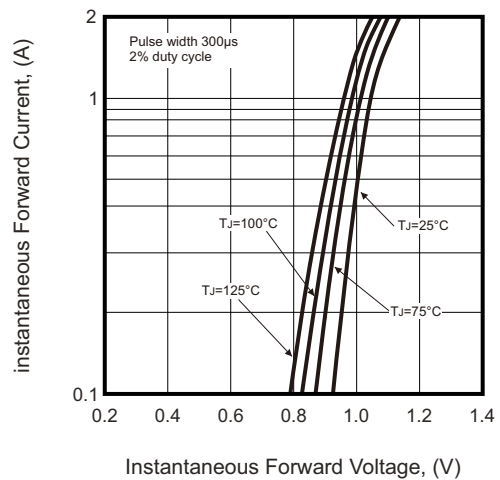
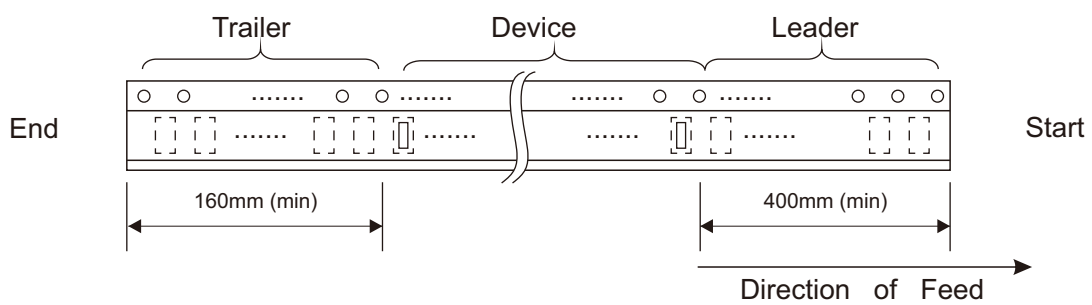
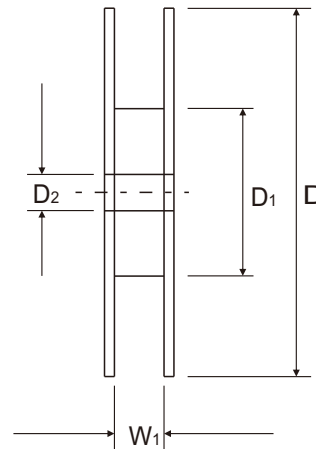
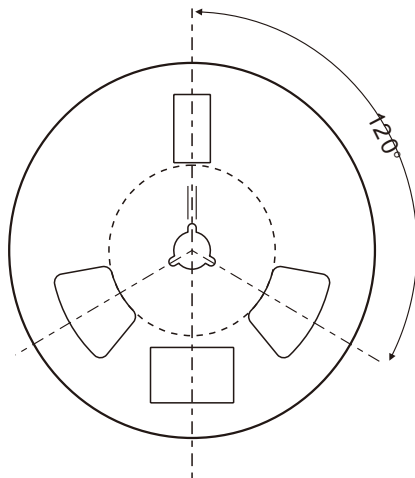
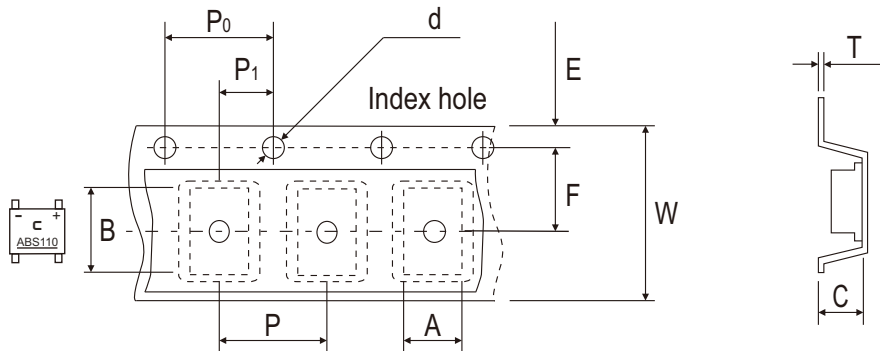


Fig.4 - Typical Forward Characteristics



Reel Taping Specification



ABS	SYMBOL	A	B	C	d	D	D1	D2
	(mm)	5.31 ± 0.10	6.68 ± 0.10	1.59 ± 0.20	1.55 ± 0.05	330	50.00 (min)	13.00 ± 0.20
	(inch)	0.209 ± 0.004	0.263 ± 0.004	0.063 ± 0.008	0.061 ± 0.002	12.992	1.969 (min)	0.512 ± 0.008

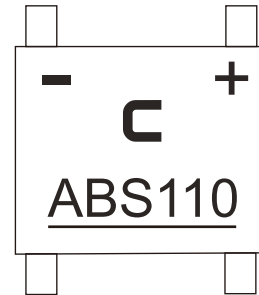
ABS	SYMBOL	E	F	P	P0	P1	T	W	W1
	(mm)	1.75 ± 0.10	5.50 ± 0.05	8.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.30	12.00 ± 0.30	12.00-14.40
	(inch)	0.069 ± 0.004	0.217 ± 0.002	0.315 ± 0.004	0.157 ± 0.004	0.079 ± 0.002	0.012	0.472 ± 0.012	0.472-0.657

Company reserves the right to improve product design, functions and reliability without notice.

REV:A

Marking Code

Part Number	Marking code
AABS110-HF	ABS110

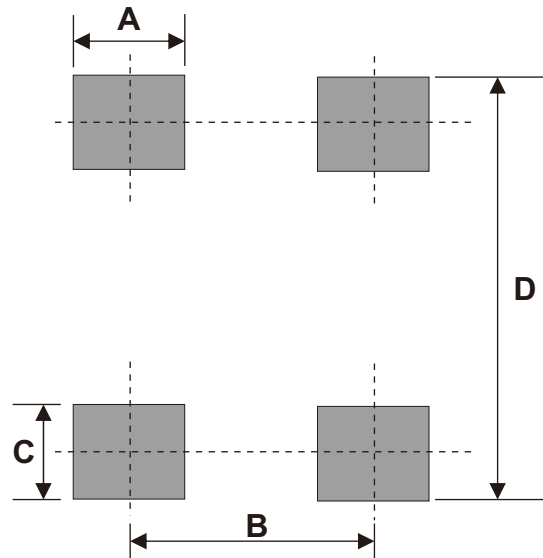


C = Comchip logo

Suggested PAD Layout

SIZE	ABS	
	(mm)	(inch)
A	0.80 Min	0.031 Min
B	4.00 REF	0.157 REF
C	0.60 Min	0.024 Min
D	6.40 Max	0.252 Max

Note: 1. The pad layout is for reference purposes only.



Standard Packaging

Case Type	REEL PACK	
	REEL (pcs)	Reel Size (inch)
ABS	5,000	13